

Amendments to the Specification

Please amend the paragraph beginning on line 2 of page 5 as follows:

The present invention provides apparatus and methods for attachment of an adhesive strip as a cover member on one or more reject die sites 36 of semiconductor package support elements 42 (~~FIG. 2a and 2B~~)(FIGS. 2A and 2B). The apparatus and ~~method~~methods of the present invention synchronously remove a coverlay film from a reel of adhesive film ~~as it cuts and applies~~while cutting and applying exact lengths of adhesive to the support element.

Please amend the paragraph beginning on line 12 of page 6 as follows:

Each reject die site 36 of the support element 42 includes a cover member 48 (cover members 48 are shown with crosshatch in FIGS. 2A-2E). The cover member 48 is attached to the reject die site 36 so as to cover from about 70% to about 100% of the corresponding wire bond slot 64 on the die site. The wire bond slot 64 is covered to prevent contamination through the slot during the encapsulation process. (The support ~~member~~element 42, wire bond slots 64, and die sites 36, 50 are illustrated in FIGS. 2A-2E prior to formation of a solder mask, solder balls or an encapsulation resin that complete formation of a semiconductor package.)

Please amend the paragraph beginning on line 9 of page 7 as follows:

Referring to FIG. 3, the adhesive dispensing apparatus 100 of the present invention applies adhesive strips to the support element 42 to function as the cover member 48, to connect a separate cover member 48 thereto (e.g., a reject die), or to attach a functional die thereto. As discussed above, cover members 48 are attached to reject die ~~sites and~~sites, and functional dice are attached to functional die sites. The apparatus and ~~method~~methods of the present invention may be used to attach adhesive strips to reject dies sites and functional die sites. Adhesive film 106 typically includes a thin layer of adhesive 116 and typically a ridged coverlay film 1123. The coverlay film 112 separates the adhesive from itself when the adhesive is spooled on a reel 104.

Please amend the paragraph beginning on line 19 of page 7 as follows:

In general, the adhesive dispensing apparatus 100 of the present invention comprises a reel of adhesive (or "film reel") 104, a drive wheel assembly 108 and a cutting assembly 126. A motor 122 is connected to the drive wheel assembly 108 to drive adhesive film 106 therethrough. The adhesive dispensing apparatus 100 further includes a pinch wheel assembly 130 positioned above the drive wheel assembly 108 to hold the coverlay film 112 between the pinch wheel assembly and the drive wheel assembly 108. A spring-loaded idler roller assembly 142 is positioned to adjust for slack that may be caused by slippage between the drive wheel assembly and the adhesive film 106.

Please amend the paragraph beginning on line 15 of page 11 as follows:

Prior to the die attachment process (and the encapsulation process), ~~defect~~defective substrates (and, thus, reject die sites) are detected and marked using conventional methods known to those persons skilled in the art. The cover member 48, such as an adhesive strip 120, may be attached to the reject die sites at a number of different stages during the semiconductor package manufacture process. The cover member 48, however, should be attached prior to the encapsulation process.